

Global Small Outline Integrated Circuit (SOIC) Package Supply, Demand and Key Producers, 2023-2029

<https://marketpublishers.com/r/GA990C765C09EN.html>

Date: January 2023

Pages: 122

Price: US\$ 4,480.00 (Single User License)

ID: GA990C765C09EN

Abstracts

A small outline integrated circuit (SOIC) is a surface-mounted integrated circuit (IC) package which occupies an area about 30–50% less than an equivalent dual in-line package (DIP), with a typical thickness being 70% less. They are generally available in the same pin-outs as their counterpart DIP ICs. The convention for naming the package is SOIC or SO followed by the number of pins.

This report studies the global Small Outline Integrated Circuit (SOIC) Package production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Small Outline Integrated Circuit (SOIC) Package, and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2022 as the base year. This report explores demand trends and competition, as well as details the characteristics of Small Outline Integrated Circuit (SOIC) Package that contribute to its increasing demand across many markets.

The global Small Outline Integrated Circuit (SOIC) Package market size is expected to reach \$ million by 2029, rising at a market growth of % CAGR during the forecast period (2023-2029).

Highlights and key features of the study

Global Small Outline Integrated Circuit (SOIC) Package total production and demand, 2018-2029, (K Units)

Global Small Outline Integrated Circuit (SOIC) Package total production value, 2018-2029, (USD Million)

Global Small Outline Integrated Circuit (SOIC) Package production by region & country, production, value, CAGR, 2018-2029, (USD Million) & (K Units)

Global Small Outline Integrated Circuit (SOIC) Package consumption by region & country, CAGR, 2018-2029 & (K Units)

U.S. VS China: Small Outline Integrated Circuit (SOIC) Package domestic production, consumption, key domestic manufacturers and share

Global Small Outline Integrated Circuit (SOIC) Package production by manufacturer, production, price, value and market share 2018-2023, (USD Million) & (K Units)

Global Small Outline Integrated Circuit (SOIC) Package production by Type, production, value, CAGR, 2018-2029, (USD Million) & (K Units)

Global Small Outline Integrated Circuit (SOIC) Package production by Application production, value, CAGR, 2018-2029, (USD Million) & (K Units)

This reports profiles key players in the global Small Outline Integrated Circuit (SOIC) Package market based on the following parameters – company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include 3M, Enplas Corporation, Toshiba Electronic Devices and Storage Corporation, Intel Corporation, Loranger International Corporation, Komachine, Aries Electronics Inc, Johnstech International and Mill-Max Manufacturing Corporation, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals, COVID-19 and Russia-Ukraine War Influence.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Small Outline Integrated Circuit (SOIC) Package market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (K Units) and average price (US\$/Unit) by

manufacturer, by Type, and by Application. Data is given for the years 2018-2029 by year with 2022 as the base year, 2023 as the estimate year, and 2024-2029 as the forecast year.

Global Small Outline Integrated Circuit (SOIC) Package Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Small Outline Integrated Circuit (SOIC) Package Market, Segmentation by Type

Mini-SOIC

Small Outline J-Lead Package

Others

Global Small Outline Integrated Circuit (SOIC) Package Market, Segmentation by Application

Industrial

Consumer Electronics

Automotive

Medical Devices

Military and Defense

Companies Profiled:

3M

Enplas Corporation

Toshiba Electronic Devices and Storage Corporation

Intel Corporation

Loranger International Corporation

Komachine

Aries Electronics Inc

Johnstech International

Mill-Max Manufacturing Corporation

Molex

Foxconn

Sensata Technologies

Plastronics

TE Connectivity

Socionext America Inc

WinWay Technology Co

ChipMOS Technologies Inc

Yamaichi Electronics

Key Questions Answered

1. How big is the global Small Outline Integrated Circuit (SOIC) Package market?
2. What is the demand of the global Small Outline Integrated Circuit (SOIC) Package market?
3. What is the year over year growth of the global Small Outline Integrated Circuit (SOIC) Package market?
4. What is the production and production value of the global Small Outline Integrated Circuit (SOIC) Package market?
5. Who are the key producers in the global Small Outline Integrated Circuit (SOIC) Package market?
6. What are the growth factors driving the market demand?

Contents

1 SUPPLY SUMMARY

- 1.1 Small Outline Integrated Circuit (SOIC) Package Introduction
- 1.2 World Small Outline Integrated Circuit (SOIC) Package Supply & Forecast
 - 1.2.1 World Small Outline Integrated Circuit (SOIC) Package Production Value (2018 & 2022 & 2029)
 - 1.2.2 World Small Outline Integrated Circuit (SOIC) Package Production (2018-2029)
 - 1.2.3 World Small Outline Integrated Circuit (SOIC) Package Pricing Trends (2018-2029)
- 1.3 World Small Outline Integrated Circuit (SOIC) Package Production by Region (Based on Production Site)
 - 1.3.1 World Small Outline Integrated Circuit (SOIC) Package Production Value by Region (2018-2029)
 - 1.3.2 World Small Outline Integrated Circuit (SOIC) Package Production by Region (2018-2029)
 - 1.3.3 World Small Outline Integrated Circuit (SOIC) Package Average Price by Region (2018-2029)
 - 1.3.4 North America Small Outline Integrated Circuit (SOIC) Package Production (2018-2029)
 - 1.3.5 Europe Small Outline Integrated Circuit (SOIC) Package Production (2018-2029)
 - 1.3.6 China Small Outline Integrated Circuit (SOIC) Package Production (2018-2029)
 - 1.3.7 Japan Small Outline Integrated Circuit (SOIC) Package Production (2018-2029)
 - 1.3.8 South Korea Small Outline Integrated Circuit (SOIC) Package Production (2018-2029)
- 1.4 Market Drivers, Restraints and Trends
 - 1.4.1 Small Outline Integrated Circuit (SOIC) Package Market Drivers
 - 1.4.2 Factors Affecting Demand
 - 1.4.3 Small Outline Integrated Circuit (SOIC) Package Major Market Trends
- 1.5 Influence of COVID-19 and Russia-Ukraine War
 - 1.5.1 Influence of COVID-19
 - 1.5.2 Influence of Russia-Ukraine War

2 DEMAND SUMMARY

- 2.1 World Small Outline Integrated Circuit (SOIC) Package Demand (2018-2029)
- 2.2 World Small Outline Integrated Circuit (SOIC) Package Consumption by Region
 - 2.2.1 World Small Outline Integrated Circuit (SOIC) Package Consumption by Region

(2018-2023)

2.2.2 World Small Outline Integrated Circuit (SOIC) Package Consumption Forecast by Region (2024-2029)

2.3 United States Small Outline Integrated Circuit (SOIC) Package Consumption (2018-2029)

2.4 China Small Outline Integrated Circuit (SOIC) Package Consumption (2018-2029)

2.5 Europe Small Outline Integrated Circuit (SOIC) Package Consumption (2018-2029)

2.6 Japan Small Outline Integrated Circuit (SOIC) Package Consumption (2018-2029)

2.7 South Korea Small Outline Integrated Circuit (SOIC) Package Consumption (2018-2029)

2.8 ASEAN Small Outline Integrated Circuit (SOIC) Package Consumption (2018-2029)

2.9 India Small Outline Integrated Circuit (SOIC) Package Consumption (2018-2029)

3 WORLD SMALL OUTLINE INTEGRATED CIRCUIT (SOIC) PACKAGE MANUFACTURERS COMPETITIVE ANALYSIS

3.1 World Small Outline Integrated Circuit (SOIC) Package Production Value by Manufacturer (2018-2023)

3.2 World Small Outline Integrated Circuit (SOIC) Package Production by Manufacturer (2018-2023)

3.3 World Small Outline Integrated Circuit (SOIC) Package Average Price by Manufacturer (2018-2023)

3.4 Small Outline Integrated Circuit (SOIC) Package Company Evaluation Quadrant

3.5 Industry Rank and Concentration Rate (CR)

3.5.1 Global Small Outline Integrated Circuit (SOIC) Package Industry Rank of Major Manufacturers

3.5.2 Global Concentration Ratios (CR4) for Small Outline Integrated Circuit (SOIC) Package in 2022

3.5.3 Global Concentration Ratios (CR8) for Small Outline Integrated Circuit (SOIC) Package in 2022

3.6 Small Outline Integrated Circuit (SOIC) Package Market: Overall Company Footprint Analysis

3.6.1 Small Outline Integrated Circuit (SOIC) Package Market: Region Footprint

3.6.2 Small Outline Integrated Circuit (SOIC) Package Market: Company Product Type Footprint

3.6.3 Small Outline Integrated Circuit (SOIC) Package Market: Company Product Application Footprint

3.7 Competitive Environment

3.7.1 Historical Structure of the Industry

- 3.7.2 Barriers of Market Entry
- 3.7.3 Factors of Competition
- 3.8 New Entrant and Capacity Expansion Plans
- 3.9 Mergers, Acquisition, Agreements, and Collaborations

4 UNITED STATES VS CHINA VS REST OF THE WORLD

4.1 United States VS China: Small Outline Integrated Circuit (SOIC) Package Production Value Comparison

4.1.1 United States VS China: Small Outline Integrated Circuit (SOIC) Package Production Value Comparison (2018 & 2022 & 2029)

4.1.2 United States VS China: Small Outline Integrated Circuit (SOIC) Package Production Value Market Share Comparison (2018 & 2022 & 2029)

4.2 United States VS China: Small Outline Integrated Circuit (SOIC) Package Production Comparison

4.2.1 United States VS China: Small Outline Integrated Circuit (SOIC) Package Production Comparison (2018 & 2022 & 2029)

4.2.2 United States VS China: Small Outline Integrated Circuit (SOIC) Package Production Market Share Comparison (2018 & 2022 & 2029)

4.3 United States VS China: Small Outline Integrated Circuit (SOIC) Package Consumption Comparison

4.3.1 United States VS China: Small Outline Integrated Circuit (SOIC) Package Consumption Comparison (2018 & 2022 & 2029)

4.3.2 United States VS China: Small Outline Integrated Circuit (SOIC) Package Consumption Market Share Comparison (2018 & 2022 & 2029)

4.4 United States Based Small Outline Integrated Circuit (SOIC) Package Manufacturers and Market Share, 2018-2023

4.4.1 United States Based Small Outline Integrated Circuit (SOIC) Package Manufacturers, Headquarters and Production Site (States, Country)

4.4.2 United States Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production Value (2018-2023)

4.4.3 United States Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production (2018-2023)

4.5 China Based Small Outline Integrated Circuit (SOIC) Package Manufacturers and Market Share

4.5.1 China Based Small Outline Integrated Circuit (SOIC) Package Manufacturers, Headquarters and Production Site (Province, Country)

4.5.2 China Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production Value (2018-2023)

4.5.3 China Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production (2018-2023)

4.6 Rest of World Based Small Outline Integrated Circuit (SOIC) Package Manufacturers and Market Share, 2018-2023

4.6.1 Rest of World Based Small Outline Integrated Circuit (SOIC) Package Manufacturers, Headquarters and Production Site (State, Country)

4.6.2 Rest of World Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production Value (2018-2023)

4.6.3 Rest of World Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production (2018-2023)

5 MARKET ANALYSIS BY TYPE

5.1 World Small Outline Integrated Circuit (SOIC) Package Market Size Overview by Type: 2018 VS 2022 VS 2029

5.2 Segment Introduction by Type

5.2.1 Mini-SOIC

5.2.2 Small Outline J-Lead Package

5.2.3 Others

5.3 Market Segment by Type

5.3.1 World Small Outline Integrated Circuit (SOIC) Package Production by Type (2018-2029)

5.3.2 World Small Outline Integrated Circuit (SOIC) Package Production Value by Type (2018-2029)

5.3.3 World Small Outline Integrated Circuit (SOIC) Package Average Price by Type (2018-2029)

6 MARKET ANALYSIS BY APPLICATION

6.1 World Small Outline Integrated Circuit (SOIC) Package Market Size Overview by Application: 2018 VS 2022 VS 2029

6.2 Segment Introduction by Application

6.2.1 Industrial

6.2.2 Consumer Electronics

6.2.3 Automotive

6.2.4 Medical Devices

6.2.5 Military and Defense

6.3 Market Segment by Application

6.3.1 World Small Outline Integrated Circuit (SOIC) Package Production by Application

(2018-2029)

6.3.2 World Small Outline Integrated Circuit (SOIC) Package Production Value by Application (2018-2029)

6.3.3 World Small Outline Integrated Circuit (SOIC) Package Average Price by Application (2018-2029)

7 COMPANY PROFILES

7.1 3M

7.1.1 3M Details

7.1.2 3M Major Business

7.1.3 3M Small Outline Integrated Circuit (SOIC) Package Product and Services

7.1.4 3M Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)

7.1.5 3M Recent Developments/Updates

7.1.6 3M Competitive Strengths & Weaknesses

7.2 Enplas Corporation

7.2.1 Enplas Corporation Details

7.2.2 Enplas Corporation Major Business

7.2.3 Enplas Corporation Small Outline Integrated Circuit (SOIC) Package Product and Services

7.2.4 Enplas Corporation Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)

7.2.5 Enplas Corporation Recent Developments/Updates

7.2.6 Enplas Corporation Competitive Strengths & Weaknesses

7.3 Toshiba Electronic Devices and Storage Corporation

7.3.1 Toshiba Electronic Devices and Storage Corporation Details

7.3.2 Toshiba Electronic Devices and Storage Corporation Major Business

7.3.3 Toshiba Electronic Devices and Storage Corporation Small Outline Integrated Circuit (SOIC) Package Product and Services

7.3.4 Toshiba Electronic Devices and Storage Corporation Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)

7.3.5 Toshiba Electronic Devices and Storage Corporation Recent Developments/Updates

7.3.6 Toshiba Electronic Devices and Storage Corporation Competitive Strengths & Weaknesses

7.4 Intel Corporation

7.4.1 Intel Corporation Details

- 7.4.2 Intel Corporation Major Business
- 7.4.3 Intel Corporation Small Outline Integrated Circuit (SOIC) Package Product and Services
- 7.4.4 Intel Corporation Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)
- 7.4.5 Intel Corporation Recent Developments/Updates
- 7.4.6 Intel Corporation Competitive Strengths & Weaknesses
- 7.5 Loranger International Corporation
 - 7.5.1 Loranger International Corporation Details
 - 7.5.2 Loranger International Corporation Major Business
 - 7.5.3 Loranger International Corporation Small Outline Integrated Circuit (SOIC) Package Product and Services
 - 7.5.4 Loranger International Corporation Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)
 - 7.5.5 Loranger International Corporation Recent Developments/Updates
 - 7.5.6 Loranger International Corporation Competitive Strengths & Weaknesses
- 7.6 Komachine
 - 7.6.1 Komachine Details
 - 7.6.2 Komachine Major Business
 - 7.6.3 Komachine Small Outline Integrated Circuit (SOIC) Package Product and Services
 - 7.6.4 Komachine Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)
 - 7.6.5 Komachine Recent Developments/Updates
 - 7.6.6 Komachine Competitive Strengths & Weaknesses
- 7.7 Aries Electronics Inc
 - 7.7.1 Aries Electronics Inc Details
 - 7.7.2 Aries Electronics Inc Major Business
 - 7.7.3 Aries Electronics Inc Small Outline Integrated Circuit (SOIC) Package Product and Services
 - 7.7.4 Aries Electronics Inc Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)
 - 7.7.5 Aries Electronics Inc Recent Developments/Updates
 - 7.7.6 Aries Electronics Inc Competitive Strengths & Weaknesses
- 7.8 Johnstech International
 - 7.8.1 Johnstech International Details
 - 7.8.2 Johnstech International Major Business
 - 7.8.3 Johnstech International Small Outline Integrated Circuit (SOIC) Package Product and Services

- 7.8.4 Johnstech International Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)
- 7.8.5 Johnstech International Recent Developments/Updates
- 7.8.6 Johnstech International Competitive Strengths & Weaknesses
- 7.9 Mill-Max Manufacturing Corporation
 - 7.9.1 Mill-Max Manufacturing Corporation Details
 - 7.9.2 Mill-Max Manufacturing Corporation Major Business
 - 7.9.3 Mill-Max Manufacturing Corporation Small Outline Integrated Circuit (SOIC) Package Product and Services
 - 7.9.4 Mill-Max Manufacturing Corporation Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)
 - 7.9.5 Mill-Max Manufacturing Corporation Recent Developments/Updates
 - 7.9.6 Mill-Max Manufacturing Corporation Competitive Strengths & Weaknesses
- 7.10 Molex
 - 7.10.1 Molex Details
 - 7.10.2 Molex Major Business
 - 7.10.3 Molex Small Outline Integrated Circuit (SOIC) Package Product and Services
 - 7.10.4 Molex Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)
 - 7.10.5 Molex Recent Developments/Updates
 - 7.10.6 Molex Competitive Strengths & Weaknesses
- 7.11 Foxconn
 - 7.11.1 Foxconn Details
 - 7.11.2 Foxconn Major Business
 - 7.11.3 Foxconn Small Outline Integrated Circuit (SOIC) Package Product and Services
 - 7.11.4 Foxconn Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)
 - 7.11.5 Foxconn Recent Developments/Updates
 - 7.11.6 Foxconn Competitive Strengths & Weaknesses
- 7.12 Sensata Technologies
 - 7.12.1 Sensata Technologies Details
 - 7.12.2 Sensata Technologies Major Business
 - 7.12.3 Sensata Technologies Small Outline Integrated Circuit (SOIC) Package Product and Services
 - 7.12.4 Sensata Technologies Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)
 - 7.12.5 Sensata Technologies Recent Developments/Updates
 - 7.12.6 Sensata Technologies Competitive Strengths & Weaknesses
- 7.13 Plastronics

- 7.13.1 Plastronics Details
- 7.13.2 Plastronics Major Business
- 7.13.3 Plastronics Small Outline Integrated Circuit (SOIC) Package Product and Services
- 7.13.4 Plastronics Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)
- 7.13.5 Plastronics Recent Developments/Updates
- 7.13.6 Plastronics Competitive Strengths & Weaknesses
- 7.14 TE Connectivity
 - 7.14.1 TE Connectivity Details
 - 7.14.2 TE Connectivity Major Business
 - 7.14.3 TE Connectivity Small Outline Integrated Circuit (SOIC) Package Product and Services
 - 7.14.4 TE Connectivity Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)
 - 7.14.5 TE Connectivity Recent Developments/Updates
 - 7.14.6 TE Connectivity Competitive Strengths & Weaknesses
- 7.15 Socionext America Inc
 - 7.15.1 Socionext America Inc Details
 - 7.15.2 Socionext America Inc Major Business
 - 7.15.3 Socionext America Inc Small Outline Integrated Circuit (SOIC) Package Product and Services
 - 7.15.4 Socionext America Inc Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)
 - 7.15.5 Socionext America Inc Recent Developments/Updates
 - 7.15.6 Socionext America Inc Competitive Strengths & Weaknesses
- 7.16 WinWay Technology Co
 - 7.16.1 WinWay Technology Co Details
 - 7.16.2 WinWay Technology Co Major Business
 - 7.16.3 WinWay Technology Co Small Outline Integrated Circuit (SOIC) Package Product and Services
 - 7.16.4 WinWay Technology Co Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)
 - 7.16.5 WinWay Technology Co Recent Developments/Updates
 - 7.16.6 WinWay Technology Co Competitive Strengths & Weaknesses
- 7.17 ChipMOS Technologies Inc
 - 7.17.1 ChipMOS Technologies Inc Details
 - 7.17.2 ChipMOS Technologies Inc Major Business
 - 7.17.3 ChipMOS Technologies Inc Small Outline Integrated Circuit (SOIC) Package

Product and Services

7.17.4 ChipMOS Technologies Inc Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)

7.17.5 ChipMOS Technologies Inc Recent Developments/Updates

7.17.6 ChipMOS Technologies Inc Competitive Strengths & Weaknesses

7.18 Yamaichi Electronics

7.18.1 Yamaichi Electronics Details

7.18.2 Yamaichi Electronics Major Business

7.18.3 Yamaichi Electronics Small Outline Integrated Circuit (SOIC) Package Product and Services

7.18.4 Yamaichi Electronics Small Outline Integrated Circuit (SOIC) Package Production, Price, Value, Gross Margin and Market Share (2018-2023)

7.18.5 Yamaichi Electronics Recent Developments/Updates

7.18.6 Yamaichi Electronics Competitive Strengths & Weaknesses

8 INDUSTRY CHAIN ANALYSIS

8.1 Small Outline Integrated Circuit (SOIC) Package Industry Chain

8.2 Small Outline Integrated Circuit (SOIC) Package Upstream Analysis

8.2.1 Small Outline Integrated Circuit (SOIC) Package Core Raw Materials

8.2.2 Main Manufacturers of Small Outline Integrated Circuit (SOIC) Package Core Raw Materials

8.3 Midstream Analysis

8.4 Downstream Analysis

8.5 Small Outline Integrated Circuit (SOIC) Package Production Mode

8.6 Small Outline Integrated Circuit (SOIC) Package Procurement Model

8.7 Small Outline Integrated Circuit (SOIC) Package Industry Sales Model and Sales Channels

8.7.1 Small Outline Integrated Circuit (SOIC) Package Sales Model

8.7.2 Small Outline Integrated Circuit (SOIC) Package Typical Customers

9 RESEARCH FINDINGS AND CONCLUSION

10 APPENDIX

10.1 Methodology

10.2 Research Process and Data Source

10.3 Disclaimer

List Of Tables

LIST OF TABLES

Table 1. World Small Outline Integrated Circuit (SOIC) Package Production Value by Region (2018, 2022 and 2029) & (USD Million)

Table 2. World Small Outline Integrated Circuit (SOIC) Package Production Value by Region (2018-2023) & (USD Million)

Table 3. World Small Outline Integrated Circuit (SOIC) Package Production Value by Region (2024-2029) & (USD Million)

Table 4. World Small Outline Integrated Circuit (SOIC) Package Production Value Market Share by Region (2018-2023)

Table 5. World Small Outline Integrated Circuit (SOIC) Package Production Value Market Share by Region (2024-2029)

Table 6. World Small Outline Integrated Circuit (SOIC) Package Production by Region (2018-2023) & (K Units)

Table 7. World Small Outline Integrated Circuit (SOIC) Package Production by Region (2024-2029) & (K Units)

Table 8. World Small Outline Integrated Circuit (SOIC) Package Production Market Share by Region (2018-2023)

Table 9. World Small Outline Integrated Circuit (SOIC) Package Production Market Share by Region (2024-2029)

Table 10. World Small Outline Integrated Circuit (SOIC) Package Average Price by Region (2018-2023) & (US\$/Unit)

Table 11. World Small Outline Integrated Circuit (SOIC) Package Average Price by Region (2024-2029) & (US\$/Unit)

Table 12. Small Outline Integrated Circuit (SOIC) Package Major Market Trends

Table 13. World Small Outline Integrated Circuit (SOIC) Package Consumption Growth Rate Forecast by Region (2018 & 2022 & 2029) & (K Units)

Table 14. World Small Outline Integrated Circuit (SOIC) Package Consumption by Region (2018-2023) & (K Units)

Table 15. World Small Outline Integrated Circuit (SOIC) Package Consumption Forecast by Region (2024-2029) & (K Units)

Table 16. World Small Outline Integrated Circuit (SOIC) Package Production Value by Manufacturer (2018-2023) & (USD Million)

Table 17. Production Value Market Share of Key Small Outline Integrated Circuit (SOIC) Package Producers in 2022

Table 18. World Small Outline Integrated Circuit (SOIC) Package Production by Manufacturer (2018-2023) & (K Units)

Table 19. Production Market Share of Key Small Outline Integrated Circuit (SOIC) Package Producers in 2022

Table 20. World Small Outline Integrated Circuit (SOIC) Package Average Price by Manufacturer (2018-2023) & (US\$/Unit)

Table 21. Global Small Outline Integrated Circuit (SOIC) Package Company Evaluation Quadrant

Table 22. World Small Outline Integrated Circuit (SOIC) Package Industry Rank of Major Manufacturers, Based on Production Value in 2022

Table 23. Head Office and Small Outline Integrated Circuit (SOIC) Package Production Site of Key Manufacturer

Table 24. Small Outline Integrated Circuit (SOIC) Package Market: Company Product Type Footprint

Table 25. Small Outline Integrated Circuit (SOIC) Package Market: Company Product Application Footprint

Table 26. Small Outline Integrated Circuit (SOIC) Package Competitive Factors

Table 27. Small Outline Integrated Circuit (SOIC) Package New Entrant and Capacity Expansion Plans

Table 28. Small Outline Integrated Circuit (SOIC) Package Mergers & Acquisitions Activity

Table 29. United States VS China Small Outline Integrated Circuit (SOIC) Package Production Value Comparison, (2018 & 2022 & 2029) & (USD Million)

Table 30. United States VS China Small Outline Integrated Circuit (SOIC) Package Production Comparison, (2018 & 2022 & 2029) & (K Units)

Table 31. United States VS China Small Outline Integrated Circuit (SOIC) Package Consumption Comparison, (2018 & 2022 & 2029) & (K Units)

Table 32. United States Based Small Outline Integrated Circuit (SOIC) Package Manufacturers, Headquarters and Production Site (States, Country)

Table 33. United States Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production Value, (2018-2023) & (USD Million)

Table 34. United States Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production Value Market Share (2018-2023)

Table 35. United States Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production (2018-2023) & (K Units)

Table 36. United States Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production Market Share (2018-2023)

Table 37. China Based Small Outline Integrated Circuit (SOIC) Package Manufacturers, Headquarters and Production Site (Province, Country)

Table 38. China Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production Value, (2018-2023) & (USD Million)

Table 39. China Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production Value Market Share (2018-2023)

Table 40. China Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production (2018-2023) & (K Units)

Table 41. China Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production Market Share (2018-2023)

Table 42. Rest of World Based Small Outline Integrated Circuit (SOIC) Package Manufacturers, Headquarters and Production Site (States, Country)

Table 43. Rest of World Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production Value, (2018-2023) & (USD Million)

Table 44. Rest of World Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production Value Market Share (2018-2023)

Table 45. Rest of World Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production (2018-2023) & (K Units)

Table 46. Rest of World Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production Market Share (2018-2023)

Table 47. World Small Outline Integrated Circuit (SOIC) Package Production Value by Type, (USD Million), 2018 & 2022 & 2029

Table 48. World Small Outline Integrated Circuit (SOIC) Package Production by Type (2018-2023) & (K Units)

Table 49. World Small Outline Integrated Circuit (SOIC) Package Production by Type (2024-2029) & (K Units)

Table 50. World Small Outline Integrated Circuit (SOIC) Package Production Value by Type (2018-2023) & (USD Million)

Table 51. World Small Outline Integrated Circuit (SOIC) Package Production Value by Type (2024-2029) & (USD Million)

Table 52. World Small Outline Integrated Circuit (SOIC) Package Average Price by Type (2018-2023) & (US\$/Unit)

Table 53. World Small Outline Integrated Circuit (SOIC) Package Average Price by Type (2024-2029) & (US\$/Unit)

Table 54. World Small Outline Integrated Circuit (SOIC) Package Production Value by Application, (USD Million), 2018 & 2022 & 2029

Table 55. World Small Outline Integrated Circuit (SOIC) Package Production by Application (2018-2023) & (K Units)

Table 56. World Small Outline Integrated Circuit (SOIC) Package Production by Application (2024-2029) & (K Units)

Table 57. World Small Outline Integrated Circuit (SOIC) Package Production Value by Application (2018-2023) & (USD Million)

Table 58. World Small Outline Integrated Circuit (SOIC) Package Production Value by

Application (2024-2029) & (USD Million)

Table 59. World Small Outline Integrated Circuit (SOIC) Package Average Price by Application (2018-2023) & (US\$/Unit)

Table 60. World Small Outline Integrated Circuit (SOIC) Package Average Price by Application (2024-2029) & (US\$/Unit)

Table 61. 3M Basic Information, Manufacturing Base and Competitors

Table 62. 3M Major Business

Table 63. 3M Small Outline Integrated Circuit (SOIC) Package Product and Services

Table 64. 3M Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)

Table 65. 3M Recent Developments/Updates

Table 66. 3M Competitive Strengths & Weaknesses

Table 67. Enplas Corporation Basic Information, Manufacturing Base and Competitors

Table 68. Enplas Corporation Major Business

Table 69. Enplas Corporation Small Outline Integrated Circuit (SOIC) Package Product and Services

Table 70. Enplas Corporation Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)

Table 71. Enplas Corporation Recent Developments/Updates

Table 72. Enplas Corporation Competitive Strengths & Weaknesses

Table 73. Toshiba Electronic Devices and Storage Corporation Basic Information, Manufacturing Base and Competitors

Table 74. Toshiba Electronic Devices and Storage Corporation Major Business

Table 75. Toshiba Electronic Devices and Storage Corporation Small Outline Integrated Circuit (SOIC) Package Product and Services

Table 76. Toshiba Electronic Devices and Storage Corporation Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)

Table 77. Toshiba Electronic Devices and Storage Corporation Recent Developments/Updates

Table 78. Toshiba Electronic Devices and Storage Corporation Competitive Strengths & Weaknesses

Table 79. Intel Corporation Basic Information, Manufacturing Base and Competitors

Table 80. Intel Corporation Major Business

Table 81. Intel Corporation Small Outline Integrated Circuit (SOIC) Package Product and Services

Table 82. Intel Corporation Small Outline Integrated Circuit (SOIC) Package Production

(K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)

Table 83. Intel Corporation Recent Developments/Updates

Table 84. Intel Corporation Competitive Strengths & Weaknesses

Table 85. Loranger International Corporation Basic Information, Manufacturing Base and Competitors

Table 86. Loranger International Corporation Major Business

Table 87. Loranger International Corporation Small Outline Integrated Circuit (SOIC) Package Product and Services

Table 88. Loranger International Corporation Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)

Table 89. Loranger International Corporation Recent Developments/Updates

Table 90. Loranger International Corporation Competitive Strengths & Weaknesses

Table 91. Komachine Basic Information, Manufacturing Base and Competitors

Table 92. Komachine Major Business

Table 93. Komachine Small Outline Integrated Circuit (SOIC) Package Product and Services

Table 94. Komachine Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)

Table 95. Komachine Recent Developments/Updates

Table 96. Komachine Competitive Strengths & Weaknesses

Table 97. Aries Electronics Inc Basic Information, Manufacturing Base and Competitors

Table 98. Aries Electronics Inc Major Business

Table 99. Aries Electronics Inc Small Outline Integrated Circuit (SOIC) Package Product and Services

Table 100. Aries Electronics Inc Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)

Table 101. Aries Electronics Inc Recent Developments/Updates

Table 102. Aries Electronics Inc Competitive Strengths & Weaknesses

Table 103. Johnstech International Basic Information, Manufacturing Base and Competitors

Table 104. Johnstech International Major Business

Table 105. Johnstech International Small Outline Integrated Circuit (SOIC) Package Product and Services

Table 106. Johnstech International Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin

and Market Share (2018-2023)

Table 107. Johnstech International Recent Developments/Updates

Table 108. Johnstech International Competitive Strengths & Weaknesses

Table 109. Mill-Max Manufacturing Corporation Basic Information, Manufacturing Base and Competitors

Table 110. Mill-Max Manufacturing Corporation Major Business

Table 111. Mill-Max Manufacturing Corporation Small Outline Integrated Circuit (SOIC) Package Product and Services

Table 112. Mill-Max Manufacturing Corporation Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)

Table 113. Mill-Max Manufacturing Corporation Recent Developments/Updates

Table 114. Mill-Max Manufacturing Corporation Competitive Strengths & Weaknesses

Table 115. Molex Basic Information, Manufacturing Base and Competitors

Table 116. Molex Major Business

Table 117. Molex Small Outline Integrated Circuit (SOIC) Package Product and Services

Table 118. Molex Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)

Table 119. Molex Recent Developments/Updates

Table 120. Molex Competitive Strengths & Weaknesses

Table 121. Foxconn Basic Information, Manufacturing Base and Competitors

Table 122. Foxconn Major Business

Table 123. Foxconn Small Outline Integrated Circuit (SOIC) Package Product and Services

Table 124. Foxconn Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)

Table 125. Foxconn Recent Developments/Updates

Table 126. Foxconn Competitive Strengths & Weaknesses

Table 127. Sensata Technologies Basic Information, Manufacturing Base and Competitors

Table 128. Sensata Technologies Major Business

Table 129. Sensata Technologies Small Outline Integrated Circuit (SOIC) Package Product and Services

Table 130. Sensata Technologies Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)

Table 131. Sensata Technologies Recent Developments/Updates
Table 132. Sensata Technologies Competitive Strengths & Weaknesses
Table 133. Plastronics Basic Information, Manufacturing Base and Competitors
Table 134. Plastronics Major Business
Table 135. Plastronics Small Outline Integrated Circuit (SOIC) Package Product and Services
Table 136. Plastronics Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)
Table 137. Plastronics Recent Developments/Updates
Table 138. Plastronics Competitive Strengths & Weaknesses
Table 139. TE Connectivity Basic Information, Manufacturing Base and Competitors
Table 140. TE Connectivity Major Business
Table 141. TE Connectivity Small Outline Integrated Circuit (SOIC) Package Product and Services
Table 142. TE Connectivity Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)
Table 143. TE Connectivity Recent Developments/Updates
Table 144. TE Connectivity Competitive Strengths & Weaknesses
Table 145. Socionext America Inc Basic Information, Manufacturing Base and Competitors
Table 146. Socionext America Inc Major Business
Table 147. Socionext America Inc Small Outline Integrated Circuit (SOIC) Package Product and Services
Table 148. Socionext America Inc Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)
Table 149. Socionext America Inc Recent Developments/Updates
Table 150. Socionext America Inc Competitive Strengths & Weaknesses
Table 151. WinWay Technology Co Basic Information, Manufacturing Base and Competitors
Table 152. WinWay Technology Co Major Business
Table 153. WinWay Technology Co Small Outline Integrated Circuit (SOIC) Package Product and Services
Table 154. WinWay Technology Co Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)
Table 155. WinWay Technology Co Recent Developments/Updates

Table 156. WinWay Technology Co Competitive Strengths & Weaknesses

Table 157. ChipMOS Technologies Inc Basic Information, Manufacturing Base and Competitors

Table 158. ChipMOS Technologies Inc Major Business

Table 159. ChipMOS Technologies Inc Small Outline Integrated Circuit (SOIC) Package Product and Services

Table 160. ChipMOS Technologies Inc Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)

Table 161. ChipMOS Technologies Inc Recent Developments/Updates

Table 162. Yamaichi Electronics Basic Information, Manufacturing Base and Competitors

Table 163. Yamaichi Electronics Major Business

Table 164. Yamaichi Electronics Small Outline Integrated Circuit (SOIC) Package Product and Services

Table 165. Yamaichi Electronics Small Outline Integrated Circuit (SOIC) Package Production (K Units), Price (US\$/Unit), Production Value (USD Million), Gross Margin and Market Share (2018-2023)

Table 166. Global Key Players of Small Outline Integrated Circuit (SOIC) Package Upstream (Raw Materials)

Table 167. Small Outline Integrated Circuit (SOIC) Package Typical Customers

Table 168. Small Outline Integrated Circuit (SOIC) Package Typical Distributors

List Of Figures

LIST OF FIGURES

Figure 1. Small Outline Integrated Circuit (SOIC) Package Picture

Figure 2. World Small Outline Integrated Circuit (SOIC) Package Production Value: 2018 & 2022 & 2029, (USD Million)

Figure 3. World Small Outline Integrated Circuit (SOIC) Package Production Value and Forecast (2018-2029) & (USD Million)

Figure 4. World Small Outline Integrated Circuit (SOIC) Package Production (2018-2029) & (K Units)

Figure 5. World Small Outline Integrated Circuit (SOIC) Package Average Price (2018-2029) & (US\$/Unit)

Figure 6. World Small Outline Integrated Circuit (SOIC) Package Production Value Market Share by Region (2018-2029)

Figure 7. World Small Outline Integrated Circuit (SOIC) Package Production Market Share by Region (2018-2029)

Figure 8. North America Small Outline Integrated Circuit (SOIC) Package Production (2018-2029) & (K Units)

Figure 9. Europe Small Outline Integrated Circuit (SOIC) Package Production (2018-2029) & (K Units)

Figure 10. China Small Outline Integrated Circuit (SOIC) Package Production (2018-2029) & (K Units)

Figure 11. Japan Small Outline Integrated Circuit (SOIC) Package Production (2018-2029) & (K Units)

Figure 12. South Korea Small Outline Integrated Circuit (SOIC) Package Production (2018-2029) & (K Units)

Figure 13. Small Outline Integrated Circuit (SOIC) Package Market Drivers

Figure 14. Factors Affecting Demand

Figure 15. World Small Outline Integrated Circuit (SOIC) Package Consumption (2018-2029) & (K Units)

Figure 16. World Small Outline Integrated Circuit (SOIC) Package Consumption Market Share by Region (2018-2029)

Figure 17. United States Small Outline Integrated Circuit (SOIC) Package Consumption (2018-2029) & (K Units)

Figure 18. China Small Outline Integrated Circuit (SOIC) Package Consumption (2018-2029) & (K Units)

Figure 19. Europe Small Outline Integrated Circuit (SOIC) Package Consumption (2018-2029) & (K Units)

Figure 20. Japan Small Outline Integrated Circuit (SOIC) Package Consumption (2018-2029) & (K Units)

Figure 21. South Korea Small Outline Integrated Circuit (SOIC) Package Consumption (2018-2029) & (K Units)

Figure 22. ASEAN Small Outline Integrated Circuit (SOIC) Package Consumption (2018-2029) & (K Units)

Figure 23. India Small Outline Integrated Circuit (SOIC) Package Consumption (2018-2029) & (K Units)

Figure 24. Producer Shipments of Small Outline Integrated Circuit (SOIC) Package by Manufacturer Revenue (\$MM) and Market Share (%): 2022

Figure 25. Global Four-firm Concentration Ratios (CR4) for Small Outline Integrated Circuit (SOIC) Package Markets in 2022

Figure 26. Global Four-firm Concentration Ratios (CR8) for Small Outline Integrated Circuit (SOIC) Package Markets in 2022

Figure 27. United States VS China: Small Outline Integrated Circuit (SOIC) Package Production Value Market Share Comparison (2018 & 2022 & 2029)

Figure 28. United States VS China: Small Outline Integrated Circuit (SOIC) Package Production Market Share Comparison (2018 & 2022 & 2029)

Figure 29. United States VS China: Small Outline Integrated Circuit (SOIC) Package Consumption Market Share Comparison (2018 & 2022 & 2029)

Figure 30. United States Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production Market Share 2022

Figure 31. China Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production Market Share 2022

Figure 32. Rest of World Based Manufacturers Small Outline Integrated Circuit (SOIC) Package Production Market Share 2022

Figure 33. World Small Outline Integrated Circuit (SOIC) Package Production Value by Type, (USD Million), 2018 & 2022 & 2029

Figure 34. World Small Outline Integrated Circuit (SOIC) Package Production Value Market Share by Type in 2022

Figure 35. Mini-SOIC

Figure 36. Small Outline J-Lead Package

Figure 37. Others

Figure 38. World Small Outline Integrated Circuit (SOIC) Package Production Market Share by Type (2018-2029)

Figure 39. World Small Outline Integrated Circuit (SOIC) Package Production Value Market Share by Type (2018-2029)

Figure 40. World Small Outline Integrated Circuit (SOIC) Package Average Price by Type (2018-2029) & (US\$/Unit)

Figure 41. World Small Outline Integrated Circuit (SOIC) Package Production Value by Application, (USD Million), 2018 & 2022 & 2029

Figure 42. World Small Outline Integrated Circuit (SOIC) Package Production Value Market Share by Application in 2022

Figure 43. Industrial

Figure 44. Consumer Electronics

Figure 45. Automotive

Figure 46. Medical Devices

Figure 47. Military and Defense

Figure 48. World Small Outline Integrated Circuit (SOIC) Package Production Market Share by Application (2018-2029)

Figure 49. World Small Outline Integrated Circuit (SOIC) Package Production Value Market Share by Application (2018-2029)

Figure 50. World Small Outline Integrated Circuit (SOIC) Package Average Price by Application (2018-2029) & (US\$/Unit)

Figure 51. Small Outline Integrated Circuit (SOIC) Package Industry Chain

Figure 52. Small Outline Integrated Circuit (SOIC) Package Procurement Model

Figure 53. Small Outline Integrated Circuit (SOIC) Package Sales Model

Figure 54. Small Outline Integrated Circuit (SOIC) Package Sales Channels, Direct Sales, and Distribution

Figure 55. Methodology

Figure 56. Research Process and Data Source

I would like to order

Product name: Global Small Outline Integrated Circuit (SOIC) Package Supply, Demand and Key Producers, 2023-2029

Product link: <https://marketpublishers.com/r/GA990C765C09EN.html>

Price: US\$ 4,480.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/GA990C765C09EN.html>